

Specification of Automotive MLCC (Reference sheet)

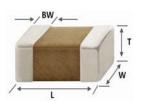


● Supplier : Samsung Electro-Mechanics ● Samsung P/N : CL10B221KC8WPNC

● AEC-Q200 Qualified

A. Dimension

Dimension



Size	0603 inch
L	1.60±0.10 mm
W	0.80±0.10 mm
Т	0.80±0.10 mm
BW	0.30±0.20 mm

B. Samsung Part Number

<u>CL</u>	<u>10</u>	<u>B</u>	<u>221</u>	<u>K</u>	<u>C</u>	<u>8</u>	<u>w</u>	<u>P</u>	<u>N</u>	<u>C</u>
1	2	3	4	(5)	6	①	8	9	10	11

① Series	Samsung Multi-layer Ceramic Capacitor		
② Size	0603 (inch code)	L: 1.60±0.10 mm	W :0.80±0.10 mm
3 Dielectric	X7R	8 Inner electrode	Ni, Open Mode Design
Capacitance	220 pF	Termination	Metal-Epoxy
⑤ Capacitance	± 10%	Plating	Sn 100% (Pb Free)
tolerance		Product	Automotive
6 Rated Voltage	100 V	Special code	Normal
7 Thickness	0.80±0.10 mm	1 Packaging	Cardboard Type, 7" Reel

C. Reliability Test and Judgement condition

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Test items	Performance	Test condition				
High Temperature	Appearance : No abnormal exterior appearance	Unpowered, 1,000hrs @ Max. temperature				
Exposure	Capacitance Change Within ±10 %	Measurement at 24±2hrs after test conclusion				
	Tan δ :0.03 max.					
	IR :More than 10,000 № or 500 №× µF	Initial Measurement 2*				
	Whichever is smaller	Final Measurement 3*				
Temperature Cycling	Appearance : No abnormal exterior appearance	1,000Cycles				
	Capacitance Change Within ±10 %	Initial Measurement 2*				
	Tan δ :0.03 max.	Final Measurement 3*				
	IR : More than 10,000 ™ or 500 ™×μF	Measurement at 24±2hrs after test conclusion				
	Whichever is smaller	1 cycle condition: -55+0/-3°C(30±3min) → Room Temp. (1min)				
		→ 125+3/-0°C(30±3min) → Room Temp. (1min)				
Destructive Physical	No Defects or abnormalities	Per EIA 469				
Analysis						
Humidity Bias	Appearance : No abnormal exterior appearance	1,000hrs 85 ℃/85%RH, Rated Voltage and 1.3~1.5V,				
	Capacitance Change Within ±12.5 %	Add 100kohm resistor				
	Tan δ : 0.035 max.	Initial Measurement 2*				
	IR :More than 500 № or 25 №× <i>µ</i> F	Final Measurement 4*				
	Whichever is smaller	Measurement at 24±2hrs after test conclusion				
		The charge/discharge current is less than 50mA.				
High Temperature	Appearance : No abnormal exterior appearance	1,000hrs @ 125℃, 200% Rated Voltage,				
Operating Life	Capacitance Change Within ±12.5 %	Initial Measurement 2*				
	Tan δ :0.035 max.	Final Measurement 4*				
	IR :More than 1,000 № or 50 №× <i>µ</i> F	Measurement at 24±2hrs after test conclusion				
	Whichever is smaller	The charge/discharge current is less than 50mA.				
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	Performance	Test condition						
External Visual	No abnormal exterior appearance	Microscope ('10)						
Physical Dimension	Within the specified dimensions	Using The calipers						
Mechanical Shock	Appearance : No abnormal exterior appearance	Three shocks in each direction should be applied along						
	Capacitance Change Within ±10 %	3 mutually perpendicular axes of the test specimen (18 shocks)						
	Tan δ, IR : Initial spec.	Peak value Duration Wave Velocity						
			1,500G	0.5ms	Half sine	4.7m/sec		
		Initial Measurement 2*				ļ		
		Final Measurement 5*						
Vibration	Appearance : No abnormal exterior appearance	5g's for 20min., 12cycles each of 3 orientations,						
	Capacitance Change Within ±10 %	Use 8'	"×5" PCB 0.	.031" Thick	7 secure p	oints on one lo	ong side	
	Tan δ, IR : Initial spec.	and 2	secure poir	nts at corne	rs of oppos	site sides. Part	s mounted	
		within	2" from any	secure po	int. Test fro	om 10~2,000Hz		
		Initial I	Measureme	ent 2*				
		Final N	Measureme	nt 5*				
Resistance to	Appearance : No abnormal exterior appearance	prehea	ating : 150°0	C for 60~12	.0 sec.			
Solder Heat	Capacitance Change Within ±10 %	Ι'	r pot : 260±					
	Tan δ, IR : Initial spec.	Initial Measurement 2*						
		Final Measurement 3*						
ESD	Appearance : No abnormal exterior appearance	AEC-Q200-002 or ISO/DIS10605						
	Capacitance Change Within ±10 %	Initial Measurement 2*						
	Tan δ, IR : Initial spec.	Final Measurement 4*						
Solderability	95% of the terminations is to be soldered	a) Preheat at 155°C for 4 hours, Immerse in solder for 5s at 245±5°						
	evenly and continuously	b) Steam aging for 8 hours, Immerse in solder for 5s at 245±5 $^{\circ}\!\mathrm{C}$						
		c) Steam aging for 8 hours, Immerse in solder for 120s at 260±5 $^{\circ}\mathrm{C}$						
		solder : a solution ethanol and rosin						
Electrical	Capacitance : Within specified tolerance	*A capacitor prior to measuring the capacitance is heat treated at						
Characterization	Tan δ : 0.025 max.	150 +0/-10 ℃ for 1hour and maintained in ambient air for 24±2 h					for 24±2 hours	
	IR(25℃): More than 10,000 ^{MΩ} or 500 ^{MΩ} × <i>μ</i> F	The Capacitance / D.F. should be measured at 25 ℃,						
	Whichever is smaller	1 ^{ktz} ± 10%, 1 ± 0.2 Vrms						
	IR(125℃) More than 1,000 № or 10 № × μF	I.R. should be measured with a DC voltage not exceeding					ding	
	Whichever is smaller	Rated	Voltage @:	25℃, @12	5℃ for 60	~120 sec.		
	Dielectric Strength	Dielectric Strength : 200% of the rated voltage for 1~5 seconds					seconds	
Board Flex	Appearance : No abnormal exterior appearance	Bendir	ng to the lim	nit, 3 mm fo	r 60 secon	ds 1*		
	Capacitance Change Within ±10 %	Initial I	Measureme	ent 2*				
		Final N	Measureme	nt 5*				
Terminal	Appearance : No abnormal exterior appearance	10 N,	for 60 sec.					
Strength(SMD)	Capacitance Change Within ±10 %	Initial I	Measureme	ent 2*				
		Final Measurement 5*						
Beam Load	Destruction value should be exceed 20 N	D N Beam speed: 0.5±0.05 mm/sec						
Temperature	X7R							
Characteristics	From -55 $^{\circ}$ C to 125 $^{\circ}$ C, Capacitance change shou	d be wi	thin ±15%					

D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260 +0/-5°C, 30sec.), Meet IPC/JEDEC J-STD-020 D Standard

- *1 : The figure indicates typical specification. Please refer to individual specifications.
- *2 : Initial measurement : Perform a heat treatment at 150 +0/-10 $^{\circ}\mathrm{C}$ for one hour after soldering process. and then let sit for 24±2 hours at room temperature. Perform the initial measurement.
- $^{\star}3$: Final measurement : Let sit for 24 \pm 2 hours at room temperature after test conclusion, then measure.
- *4 : Final measurement : Perform a heat treatment at 150 +0/-10 °C for one hour after soldering process. and then let sit for 24±2 hours at room temperature. Perform the initial measurement.
- *5 : Final measurement : Let measure within 24 hours at room temperature after test conclusion.



Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

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- ② Medical equipment
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- 4 Disaster prevention/crime prevention equipment
- ⑤ Power plant control equipment
- 6 Atomic energy-related equipment
- ① Undersea equipment
- 8 Traffic signal equipment
- Data-processing equipment
- @ Electric heating apparatus, burning equipment
- Safety equipment
- @ Any other applications with the same as or similar complexity or reliability to the applications